PRESENTED BY



2016 AUTOMOTIVE EMC



WELCOME TO MEGA AUTOMOTIVE

Joanna Hill

AUTOMOTIVE ELECTROMAGNETIC COMPATIBILITY (EMC) STANDARDS

Time Is Money, Can You Afford To Lose Either?



Use Our MultiStar Multi-Tone Tester

EMC test accuracy is critical. But taking too long to test can be costly and delays time to market. With the speed of the revolutionary MultiStar Multi-Tone tester, you don't have to dwell on tedious EMC radiated immunity testing anymore.

Maximize your efforts by testing multiple frequencies simultaneously, which increases testing speed, gets your product to market faster,

eliminates costly chamber bottlenecks and mimics real world threats.

With the ability to test from 30 Hz to 6 GHz, the MultiStar Multi-Tone Tester meets radiated and conducted immunity requirements of Commercial, Automotive, Aviation and Military standards such as:

- IEC 61000-4-3 and IEC 61000-4-6
- ISO 11452-2, -3, -4 (BCI and TWC) and -5
- DO-160 Sections 18 and 20
- MIL-STD-461 CS101, CS109, CS114, RS101, RS103



IEC 61000-4-3, 1% step sizes, taking into account dwell time

So, if you believe lost time is lost money, don't dwell on it. Ask about our new MultiStar Multi-Tone Tester. Amazing speed. Incredible accuracy.

Visit us at www.arworld.us/MultiTone or call 215-723-8181.

ISO 9001:2008 Certified We don't just build great products.
We build great products that last.





rf/microwave instrumentation

TOYO AD PLACEMENT

TABLE OF CONTENTS

6	Automotive EMC Manufacturers Guide AUTHOR NAME Title
15	Does Your automotive Printed Circuit Board Have Too Many Grounds?
	DR. TODD H. HUBING LearnEMC
20	Welcome to Mega Automotive JOANNA HILL JPHill, LLC
23	Automotive Electromagnetic Compatibility (EMC) Standards
26	Automotive Groups, Organizations,

INTRODUCTION

Kenneth Wyatt

Sr. Technical Editor, Interference Technology Email: kwyatt@interferencetechnology.com



Today, we're witnessing many new disruptive technologies. One of the biggest involves the automobile. For decades, automobile engines have been driven by explosive gasses in cylinders, which push mechanical crankshafts. One of the most exciting technologies today is the current development of electric and semi-autonomous (driver assisted) or fully-autonomous vehicles.

While some major auto manufacturers have tested the waters of hybrid and all-electric vehicle production, it wasn't until Tesla started making big moves and investing in an extensive worldwide system of charging stations that the major manufacturers finally took serious notice. Now every manufacturer is rapidly developing production electric vehicles and related intra-vehicle and vehicle-to-vehicle communications and control.

There are numerous trial programs ongoing throughout the U.S. and Europe. Google's self-driving program was among the first, and Autoliv (a German company) has been running a pilot program in the Boston area for several months now, gathering data in both rural and congested city streets.

Federal and state authorities are also rethinking the regulations regarding autonomous vehicles. For example, California's department of motor vehicles said Sept 30, 2016 that the most advanced self-driving cars will no longer be required to have a licensed driver aboard, so long as federal approval is given. The U.S. Department of Transportation has also recently issued a comprehensive policy on self-driving cars. In Europe, driverless cars may actually start with trucks. There's been some research on the concept of convoys of autonomous semi-trucks ("lorries" if in Europe).

One interesting question is, "How will driverless cars make life or death choices?" For example, let's say an autonomous vehicle rounds a corner and there is a school bus, kids crossing the street, and trees on either side of the street. Assuming the brakes won't stop the vehicle in time, how will the software decide what to do; hit the bus, the kids, or the trees? Our keynote speaker, Robert Neff, will be addressing this issue during the upcoming EMC Live Test & Design Bootcamp, November 16th.

In other areas, much research is going into fully autonomous farming equipment, such as combines. The U.S. Navy is also getting into the act with a fully autonomous (scaled down) ship, which is currently on trials off the Pacific Coast.

Ride-sharing companies like Uber and Lyft are seriously considering self-driving cars. Uber has been more on the forefront with pilot programs already occurring in San Francisco and Pittsburg. Interestingly, there is a trend, especially among millennials and urban residents, to give up owning a personal vehicle and move towards the likes of Uber, Lyft, or Zoomcar (and others).

In Indianapolis recently, I noticed the prevalence of "BlueCars" throughout the downtown area. This is the largest concentration of electric ride sharing cars in the U.S. (see photo). Manufactured by Bolloré Group (Paris), the company has funded a trial program to include up to 500 vehicles, 200 service locations, and 1000 charging stations. Once pre-qualified, you can grab the nearest car and when finished, return it to one of many labeled parking spots for very reasonable cost.

From an EMC point of view, all this new electric vehicle and self-driving technology, system infrastructure, and vehicle-to-vehicle control technology will require extensive design, simulation, and testing. New equipment for evaluating radar, Lidar, intra-vehicle, and vehicle-to-vehicle command and control will be required.

We EMC design and test engineers will be required to learn new technologies and test methods for the 70 GHz anti-collision radars, the laser-ranging Lidar, new 5G vehicle-to-vehicle communications, and the myriad of on-board vehicular control and command systems required. All these systems needs to "play well" together, or we could potentially see unthinkable carnage on the roadways. As ever, we at Interference Technology will stay at the forefront of this technology and help keep you informed of the latest trends and test requirements.



AUTOMOTIVE EMC MANUFACTURERS GUIDE



Į.	Type of Equipment															
Manufacturer	Contact Information - URL	Antennas	Amplifiers	Spectrum Analyzers/EMI Receivers	ESD Simulators	Emissions Equipment	Immunity Equipment	Battery Simulation Test	5G Test Equipment	Radar Test (70 GHz)	Lidar Test Equipment	Wireless Test Equipment	Signal Generators	RF Field Probes		
A.H. Systems	http://www.ahsystems.com		X													
Advanced test Equipment Rentals	http://www.atecorp.com/category/emc- compliance-esd-rfi-emi.aspx	χ	χ	χ		χ	χ		χ	Х		χ	χ	χ		
Anritsu	http://anritsu17-px.rtrk.com/en-US/test- measurement/industries/automotive/			χ		χ						χ	χ			
EM Test	http://www.emtest.com/home.php						χ	χ								
Empower RF Systems	http://www.empowerrf.com		χ													
Gauss Instruments	https://www.gauss-instruments.com/en/			χ												
Haefley-Hippotronics	http://www.haefely-hipotronics.com/ product-filter/emc-test-equipment/				χ		χ									
Instruments For Industry (IFI)	http://www.ifi.com		χ													
Keysight	http://www.keysight.com/main/home. ispx?cc=US&lc=eng			Х		X			χ	Х		χ	χ			
Milmega	http://www.milmega.co.uk		χ													
Narda/PMM	http://www.narda-sts.it/narda/default_en.asp	χ	Х	X		χ	X									
Ophir RF	http://ophirrf.com		χ													
Rohde & Schwarz	https://www.rohde-schwarz.com/us/ home 48230.html	X	X	Х		χ	χ		χ	Х		χ	χ	χ		
Spes Development	http://spesdev.com							χ								
Tektronix	http://www.tek.com			X					X			χ				
Teseq	http://www.teseq.com/en/index.php		Х		χ		χ	χ								
Trabsient Specialists	http://www.transientspecialists.com						χ	χ								
TRSRenTelCo	https://www.trs-rentelco.com/ SubCategory/EMC Test Equipment.aspx	Х	Х	X		χ	χ		χ	X		χ	χ	X		
Vectawave Technology	http://vectawave.com		Х													

EP-600 series

USB/RS232 Electric Field Probes

EP-600 series features EP-600, EP-601, EP-602, EP-603, EP-604



Main Features

- 5 kHz to 26.5 GHz frequency range
- Up to 66 dB dynamic, single range
- Symmetrical dipole configuration
- Excellent isotropy (down to 0,2 dB typical)
- Up to 40 meters communication by Fiber Optic Cable
- Up to 80 hours of operation before recharging
- High performance, high reliability Li-Mn battery
- PC direct connection via Optical to RS232/USB adapters
- Extremely lightweight: 22 g only!

The all-in-one that sets the standard for miniature optically coupled broadband E-field isotropic probes

Exceptionally small-sized spherical symmetrical configuration, lightweight and miniaturized electronics combined with excellent RF characteristics make the EP-600 series RF Electric Field Probes the ideal solution for all EMC/EMI applications (chambers and TEM/GTEM cells), biology and materials research and wherever fast and accurate measurements with negligible or minimum interference of the probe to the field under measure are essential. Accredited calibration on request.





9010 FAST

High Speed. Low Uncertainty.



New extension FR4003
Rod Antenna and
CISPR/MIL-STD EMI Receiver
In a unique solution

3 Extensions Receiver:

- 30 MHz 3 GHz
- 30 MHz 6 GHz
- 6 GHz 18 GHz

FFT Gapless EMI Receiver

Full compliance to CISPR and MIL-STD

Direct antenna mounting modules

Digital Fiber optic link up to 100m







Narda's PMM FR4003 is the new reference in radiated emission tests to 30 MHz:

- Integrates a full CISPR and MIL-STD EMI receiver no external units needed
- The fiber optic USB PC link frees of the negative effects due to the coaxial cable
- Saturation-free operation thanks to the automatic preselection filters
- Great sensitivity thanks to the integrated preamplifier
- Internal capacimeter for accurate check of the ambient influence and proper grounding
- Internal reference source for easy, on-site calibration
- Plug-in rechargeable battery
- RF output for connecting existing receivers
- Powerful PC software included, with advanced functions like waterfall, spectrogram etc.





L1-150M L1-150M1



L1-150M and L1-150M1 are single-path LISN (AMN) designed for conducted disturbances measurements according to different standards for Automotive and ISM applications.

Selecting the standard is as easy as turning a rear panel switch.

PMM's LISN are robust, stable, made with high-quality components, designed for perfect grounding and safe connections.

Characteristics:

- L1-150M: 100 kHz to 200 MHz
- L1-150M1: 10 kHz to 400 MHz
- Multi-standard seclection: CISPR 16-1-2, CISPR 25, ISO 11452-2/4/5, ISO 7637-2
- MIL-STD-461F, DO-160, ED-14G
- 50 A max output current
- Line voltages 600 VDC, 300 VAC 50÷400 Hz
- Bolt terminals for safe and stable connections
- Large baseplate for optimal grounding
- Robust, compact construction







Introducing our new Common Mode Choke Finder



There's nothing common about it!

Search and compare hundreds of common mode choke options in four easy steps.

Step 1: Search parts by Impedance, Attenuation or Inductance at your operating frequency.

Step 2: View results in a sortable table with complete performance specifications and select parts for further analysis.

Step 3: Make direct comparisons of up to six components on single impedance and attenuation graphs.

Step 4: Request free samples of the most interesting parts for evaluation and testing.

It's that Simple!

Try it at coilcraft.com/CMCfinder.





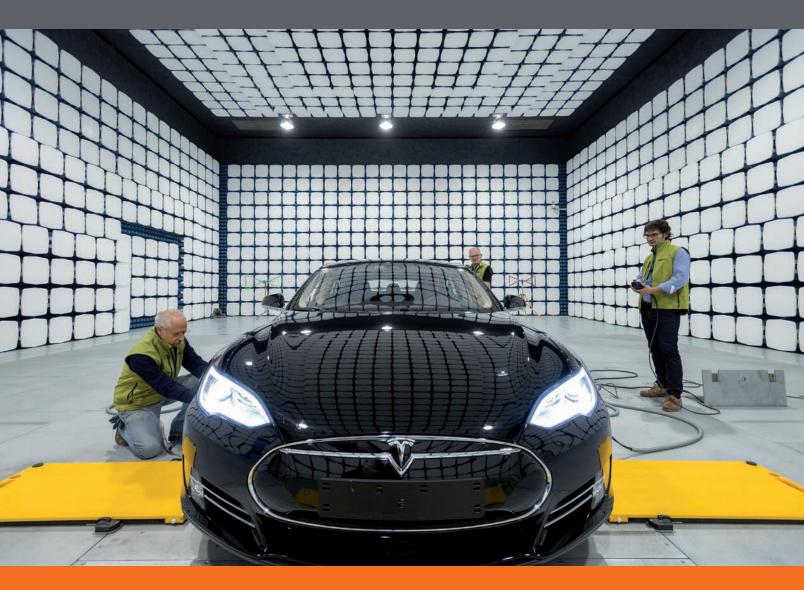


First Choice for EMC Testing!

For EMC Solutions we Design, Manufacture, Supply and Install:

- Anechoic & Semi-Anechoic Chambers
- Absorbing Materials
- Shielded Rooms
- Shielded Doors

- Turntables, Masts & Controllers
- EMC Antennas
- EMP Protection







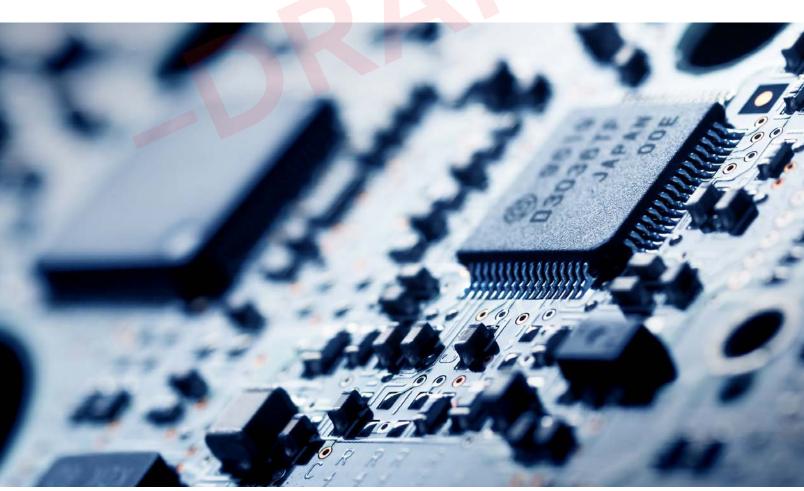
DOES YOUR AUTOMOTIVE PRINTED CIRCUIT BOARD HAVE TOO MANY GROUNDS?



Dr. Todd H. Hubing LearnEMC hubing@LearnEMC.com

Dr. Todd Hubing is a Professor Emeritus of Electrical and Computer Engineering at Clemson University and President of LearnEMC. Dr. Hubing holds a BSEE degree from MIT, an MSEE degree from Purdue University and a Ph.D. from North Carolina State University. He was an engineer at IBM for 7 years and a faculty member at the University of Missouri-Rolla for 17

years before joining Clemson University in 2006. As the Michelin Professor of Vehicle Electronics at Clemson, he established the Clemson Vehicular Electronics Laboratory where he supervised research projects and taught classes in vehicle electronics, electromagnetic compatibility and digital signal integrity. At LearnEMC, he provides EMC instruction, consulting and design assistance to engineers working in the automotive, aerospace and consumer electronics industries. Dr. Hubing has authored or co-authored over 200 papers and presentations on electromagnetic modeling, electromagnetic compatibility and the design of reliable electronic systems. He is a Fellow of the Institute of Electrical and Electronics Engineers (IEEE), a Fellow of the Applied Computational Electromagnetics Society, and a Past-President of the IEEE Electromagnetic Compatibility Society. He may be contacted at hubing@ LearnEMC.com



DOES YOUR AUTOMOTIVE PRINTED CIRCUIT BOARD HAVE TOO MANY GROUNDS?

Abstract

One of the most widespread design defects in automotive printed circuit boards is the lack of an established high-frequency reference ground. This problem is exacerbated by a tendency among automotive design engineers to cut up solid current return planes in an attempt to establish "noisy" and "quiet" grounds.

Introduction

Too often, the designers of automotive electronic systems shoot themselves in the foot (so to speak), making design decisions that ultimately make it difficult for their products to meet the automotive EMC requirements. Basic design flaws such as improper grounding, poor trace routing, and ineffective decoupling are widespread throughout the industry. Many designs also fail to control the routing of currents induced by immunity tests such as bulk current injection or electrical fast transient testing.

Historically, the significance of these design flaws has been diminished by relatively long development cycles that allowed a test-and-fix design strategy. EMC problems that couldn't be fixed were often dealt with by waiving the requirement. Today however, a growing number of electronic systems play a critical role in automotive safety. There is no opportunity to experiment with multiple iterations of the hardware design during development; and waivers of EMC requirements are becoming harder to obtain.

This article addresses one of the most widespread and damaging design flaws in automotive printed circuit boards today, the lack of a single high-frequency ground reference. More specifically, there is a tendency among automotive circuit board designers to over-partition their "ground" planes.

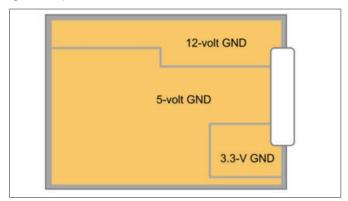


Figure 1. A circuit board with isolated "grounds" for 12-volt, 5-volt and 3.3-volt components.

What's the Problem?

It is not uncommon for an automotive circuit board to

have multiple "grounds". For example, as illustrated in *Figure 1*, there may be one ground for the 12-volt devices, one ground for the 5-volt devices, and a separate ground for the 3.3-volt digital logic. It is also not uncommon to see isolated grounds for analog sensors, power supplies, motor drivers, memory devices or anything else that is considered particularly noisy or susceptible to noise. Decisions to isolate various grounds are motivated by a desire to reduce interference between various circuits on the board. Usually, this is done without any attempt to quantify the amount of interference that would have resulted if the grounds had not been isolated (even though this is a simple calculation).

The problem with isolating the voltage references (ground) of various circuits on a printed circuit board is illustrated in *Figure 2*. Isolated grounds are not held to the same potential, i.e. there is likely to be a voltage difference between them. That means there is likely to be a voltage difference between circuits referenced to different grounds. If those circuits communicate with each other on the board, that voltage difference appears as noise on the signals. If those circuits communicate with circuits off the board, then wires leaving the board have a voltage difference between them.

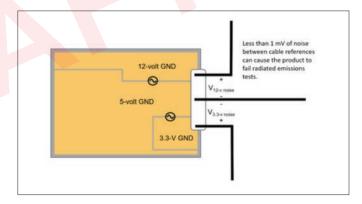


Figure 2. Illustration of the voltage differences between "grounds" driving unpaired wires in a harness.

At frequencies where radiated emissions are likely to be a concern, a voltage as low as 1 mV between unpaired wires in a wiring harness can result in EMC test failures. [In some frequency bands, 0.1 mV is sufficient to cause a failure.] In order to ensure that a design complies with radiated emissions requirements (and for similar reasons, radiated immunity requirements), it is extremely important to maintain a single RF ground reference for every circuit connected to a wiring harness. Ensuring that all of the wires in a harness are held to the same potential (within 0.1 mV) at RF frequencies is relatively straightforward in a design with a single solid ground plane; but it can be extremely difficult in boards with isolated grounds.

Why Isolate Grounds?

If isolating grounds is such a bad practice, why are so

many boards designed that way? Often, the answer is that the designers were following the advice of a component supplier's application note, or they were simply mimicking the design of a product that had been successful in the past. There is one valid reason that a board designer might not want to let two circuits share the same ground plane. That is to prevent common-impedance coupling. Common-impedance coupling (or conducted coupling) occurs when two circuits share parts of their current paths. Currents from the circuit behaving as the noise source flowing in the shared part induces a voltage in both circuits. For example the two circuits represented schematically in Figure 3 share the same current return path. The impedance of that return path is RRET. If Circuit 1 (the outer loop) creates a current, IRET, flowing in the return path, then a voltage is developed across the return path, VRET = IRET RRET. By Kirchhoff's voltage law, some of this voltage will appear across the Circuit 2 source, and the rest will appear across the Circuit 2 load.

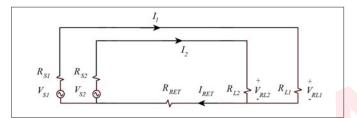


Figure 3. Two circuits sharing the same current return conductor.

Common-impedance coupling is one of four EM coupling mechanisms, along with electric-field coupling, magnetic-field coupling and radiation coupling. Common-impedance coupling is most likely to be important at relatively low frequencies when the source circuits have relatively low impedance. The two most common methods for reducing common-impedance coupling are to reduce the impedance of the shared part of the circuit, or to isolate the circuits so that they don't share a current path.

Providing separate "grounds" for various circuits on a circuit board is one method for reducing the common-impedance coupling between these circuits. This can be effective if high-current circuits use the ground plane as part of their current return path, and if that path is shared by circuits sensitive to small noise voltages. It is important to note that isolating current-return paths by partitioning a solid copper plane is only effective for reducing common-impedance coupling. The other EM coupling mechanisms are generally not affected by partitioning the return plane. In fact, gapping a solid ground plane can actually increase the electric and magnetic field coupling between traces routed over different portions of the plane.

When Should Current Returns be Isolated?

Designs that isolate current return conductors are justified when common-impedance coupling is a significant concern. Unlike high-frequency currents, low-frequency (e.g. below 100 kHz) currents flowing on a printed circuit

plane will spread out. This means that all circuits that use a "ground" plane to return low-frequency currents share a portion of their current paths.

In these situations, it's relatively easy to quantify the maximum possible common-impedance coupling. The maximum possible voltage coupled to a victim circuit is equal to the maximum resistance of the plane times the maximum current produced by the source circuit. For example, consider the two circuits illustrated in *Figure 4*. A 3.3-volt digital signal shares the same current return plane as an actuator signal that can switch from 0 amperes to 10 amperes in less than 1 microsecond. To calculate the maximum possible common-impedance coupling, we'll assume that the traces are near each other and calculate the coupling that would occur if they both ran the entire length of the board.

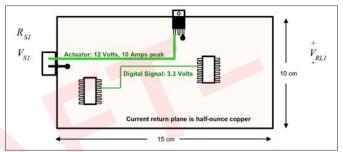


Figure 4. Two circuits sharing the same current return plane.

Since the plane is half-ounce copper (~17.8 µm thick), it has an end-to-end resistance of approximately,

$$R = \frac{\sigma A}{\sigma A}$$

$$= \frac{0.15 \text{ m}}{(5.8 \times 10^7 \text{ S/m})(0.10 \text{ m})(17.8 \times 10^{-6} \text{ m})} = 1.5 \text{ m}\Omega$$
(1)

Therefore, the maximum coupled voltage due to common-impedance coupling is,

$$V_{coupled} \le (1.5 \times 10^{-3} \,\Omega)(10 \,\mathrm{A})$$

$$\le 15 \,\mathrm{mV}$$
 (2)

Clearly, in this case, it is ok to allow these two signals to share the same current return plane. In fact, a few amperes of low-frequency current will generally translate to a few millivolts in a printed circuit board ground plane; so it is rarely necessary to provide an isolated return plane.

In rare situations where a calculation shows that low-frequency isolation is necessary, it is usually better to route the source or victim return currents on traces that occupy a different layer leaving the ground plane undivided. Generally, if two large grounds are isolated at low frequencies, they must still be connected at high frequencies in order to avoid radiated emissions and radiated immunity issues. Routing current returns on different layers facili-

tates their connection at high frequencies using capacitors with low connection inductance.

The fact that the current switched in less than 1 microsecond was not a factor in this calculation. That's because the dominant common impedance at low frequencies is the resistance of the plane. The coupled voltage waveform will mimic the shape of the source current waveform and the amount of common-impedance coupling will not depend on the rate of change of the signal. In the example above, electric-field and/or magnetic-field coupling would certainly be a significant concern. The field coupling would make it necessary to separate these traces. Nevertheless, it is critical to note that isolating the actuator's return plane from the digital signal's return plane would NOT significantly reduce the electric or magnetic field coupling.

Does Your Board Have Too Many Grounds?

It typically requires hundreds of millivolts of noise in order to interfere with digital logic. So unless the interfering circuits are switching hundreds of amperes of current, it is generally fine to allow these circuits to share a current return plane. Likewise digital logic, which typically switches peak currents on the order of hundreds of milliamps, can readily share a return plane with analog circuits capable of tolerating a few hundred microvolts of induced noise. Simple common-impedance coupling calculations like those in (1) and (2), will tell you if you need to isolate your current return paths at low frequencies.

At frequencies above 100 kHz, currents returning on a plane are concentrated beneath the signal trace. Common-impedance coupling is easily avoided by providing separation between the signal traces. Separating the traces is also generally effective for reducing electric and magnetic field coupling, which are much more likely to be the dominant coupling mechanisms at high frequencies.

A good rule of thumb when laying out automotive printed circuit boards is, "Never gap a solid ground plane." In situations where it is necessary to isolate low-frequency return currents, route the return currents of either the source or the victim circuits on a different layer. This will make it easier to re-establish a connection between these "grounds" at high frequencies in order to meet radiated emissions and immunity requirements.



Please Feel Free to Contact the Author for Any Questions at: hubing@LearnEMC.com



ONLINE EVENT

November 16, 2016

A 1-day, highly focused online event for test, design, and electronics engineers, dedicated to pre-compliance and compliance testing and designing for EMC. Learn the latest on standards, equipment, setups and test techniques.

For more information about Technical Programs, EMC Resources, Sponsors & Presenters please visit:

tb.emclive2016.com

WELCOME TO MEGA AUTOMOTIVE



Joanna Hill JPHill, LLC joannaemc@icloud.com

Joanna Hill holds a MSEE from Georgia Institute of Technology and a BSEE from Florida Institute of Technology. She turns the magic of EMC into the technology of EMC with consulting and classes globally. Her classes have demystified EMC in China, Mexico, Germany and the United States.

She is a member of the IEEE, IEEE EMC Society, SWE, SAE EMI Task Force, ISO TC22/SC3/WG3 USTAG, and CIS-PR/D USTAG. And a member of the IEEE EMC Society board of directors. She has worked as an engineer for 39 years always with an interest in fields and waves. Her LinkedIn page URL is: http://www.linkedin.com/in/JoannaE-MC. She may be contacted at: joannaemc@icloud.com.



WELCOME TO MEGA AUTOMOTIVE

Today is Arnold's first day at Mega Automotive. He is fresh out of collage with an electrical engineering degree and is eager to meet his new boss, Mr. Buttsworth.

Mr. Buttsworth: Hello Arnold welcome to Mega Automotive. I'm sure you're going to like it here. It's a fast-paced environment with lots to learn and loads of good people to work with. We have an exciting new position for you it's called a Component Electromagnetic Compatibility Engineer. Your job is to prevent Electromagnetic Compatibility failures at final vehicle testing. We design the vehicle and many of the components. Some of the component are designed and manufactured by suppliers. After all the parts have been designed they are assembled into prototype vehicles. These vehicles are then tested to make sure they can meet all sorts of requirements; one of these requirements is Electromagnetic Compatibility.

First, you must understand the specific EMC tests we perform on a vehicle are considered a company intellectual property and you are not allowed to disclose these requirements outside of the company.

Arnold, your first assignment will be to test an engine controller for EMC as a component. You are to develop a component level test plan to catch the EMC issues so they can be fixed early in the programs rather then at the end of a program. It is very expensive to make any last minute changes. This is what an Engine Control Unit looks like, we call it an ECU.



An Engine Controller Unit (ECU) from a 1996 Chevrolet Beretta courtesy of Delco Electronics and Wikipedia.

Arnold: Cool, I love working on cars. It'll be great fun to work on them for a living. What exactly is EMC?

Mr. Buttsworth: Our vehicles are put into a lot of different electromagnetic fields created by a lot of different devices. Many of these devices are "self-certified". In fact, automobiles are also "self-certified". That means that Mega Automotive is obligated to make sure a vehicle will work correctly when exposed to the fields that it may encounter and not interfere with any other device. The problem is

that not all of the companies making things are as diligent as we are here at Mega Automotive.

For example, farms can have a water sprinkler called a Pivot that is driven by a three phase, 480 volt, Variable Frequency Drive. The VFD takes in 60 cycle AC and makes whatever frequency you want at 480 volts and 800 amps. The variable frequency is used to drive the pump motor of the sprinkler. The VFD does this by rectifying the three phases with a bank of diodes and capacitors. Then this DC voltage is pulse width modulated to feed a three phase motor that drives the water pump. If any of the case ground connections in the wet and dirty farm environment gets rusty, a PN junction is formed in the ground path. This splatters RF noise all over the spectrum. To make matters worse, the pump drives water into a 16 foot high quarter mile long water pipe.

The farmer thinks of this as an agricultural sized water sprinkler, we know it as a folded monopole antenna driven by lots of high frequency PWM noise. The Farmer has no idea he is creating huge electromagnetic fields that can interfere with all sorts of devices including vehicles. And to make matters worse, occasionally this quarter mile long short wave antenna with taps every 50 feet made up of an A-frame with two tractor tires to elevate the water pipe is parallel to the highway! Never the less our vehicles driving by within 100 feet of this antenna are not allowed to misbehave.

Your job is to come up with a component level EMC test to make sure that when the initial prototype is assembled and tested there will not be any issues with EMC.

Arnold: Okay, can I see the harness of wires that will be connected to the ECU?

Mr. Buttsworth: No, it has not been designed yet.

Arnold: Okay, can I know how many harnesses will be connected to the ECU?

Mr. Buttsworth: No, it has not been designed yet.

Arnold: Are there things connected to this unknown harness?

Mr. Buttsworth: Yes, we know what kind of sensors and actuators will be connected to the ECU and we have the documents that describe their function, but we don't actually have any of then yet. They're all in design as we speak.

Arnold: Okay, can I see the schematic of the ECU?

Mr. Buttsworth: No, it has not been designed yet.

Arnold: What can I know about this thing?

2016 AUTOMOTIVE EMC GUIDE

Mr. Buttsworth: We know the pinout and we have a description of the engine control system. After the harness have been designed and routed on the engine and when we find out how the engine group is going to ground the ECU, it will be assemble into a prototype vehicle and it has to pass the vehicle EMC testing.

Let me show you to your desk. We will have a computer for you shortly. In the mean time please read these documents. And here is your list of mandatory safety and company training classes.

Barney: Hello Arnold, welcome to the neighborhood. I hear you're the new EMC component engineer. I do the vehicle level EMC testing.

Arnold: Oh boy am I glad to meet you. I am to develop an EMC test to prevent issues from showing up in your EMC testing. But I have to do this without knowing how the thing is going to be wire up. This is impossible.

Barney: Actually our job is to write test plans that specifies the EMC test that need to be run by EMC technicians. The EMC equipment itself is very expensive and getting chamber time is really hard. So we write an EMC test plan, it gets approved, and then performed by the technicians.

All you have to do is come up with an idealized harness with a load box to simulate the sensors and actuators at the end of the harness. Make the harness about half a wavelength long in the FM band and pass on the test equipment design to the test equipment group. Tell them

to test for stuck at one and zero for all loads.

It's not really that hard if you don't get too picky about simulating the vehicle. We have no idea what it will look like at this point, but never the less it has to pass my vehicle level EMC test to be sold. And we cannot delay the first day of production of the vehicle if it fails the EMC testing. As a result we almost always end up working nights and weekends to get it out the door in time.

Good luck and welcome to automotive. It's not for everyone, but I love it, to seen my vehicles on the show room floor or on the road. You know you had a part of making it happen. We have lunch down in the cafeteria. I'll come by around noon to show you where it is. By the way, the hardest part of the job is staying awake while you read all of the documentation. See you at noon.

Epilogue

After many years of trial and error, Arnold came up with a technique to test modules for EMC before the vehicle design was complete. At the same time others were also working to solve the same problem thought out the industry. But as you can expect their solutions were all different. Some demanded the load box be in plastic, where others wanted metal. All of these imperial techniques worked, sort of. But still at the end of a vehicle program, it must pass an EMC test.

Disclaimer, the individuals named in this article are fictional, any reference to actual people or companies is unintended.



Please Feel Free to Contact the Author for Any Questions at: joannaemc@icloud.com

AUTOMOTIVE ELECTROMAGNETIC COMPATIBILITY (EMC) STANDARDS

The following list of automotive EMC standards was developed by Dr. Todd Hubing, Professor Emeritus of Clemson University Vehicular Electronics Lab (http://www.cvel.clemson.edu/auto/auto_emc_standards.html). A few of these standards have been made public and are linked below, but many others are considered company confidential and are only available to approved automotive vendors or test equipment manufacturers. While several standards are linked on this list, an internet search may help locate additional documents that have been made public. Permission to republish has been approved.

CISPR (Autom	otive Emissions Requirements)					
Document Number	Title					
CISPR 12	Vehicles, boats, and internal combustion engine driven devices – Radio disturbance characteristics – Limits and methods of measurement for the protection of receivers except those installed in the vehicle/boat/device itself or in adjacent vehicles/boats/devices					
CISPR 25	Radio disturbance characteristics for the protection of receivers used on board vehicles, boats, and on devices – Limits and methods of measurement					
ISO (Automot	ive Immunity Requirements)					
Document Number	Title					
ISO 7637-1	Road vehicles – Electrical disturbances from conduction and coupling – Part 1: Definitions and general considerations					
ISO 7637-2	Road vehicles – Electrical disturbances from conduction and coupling – Part 2: Electrical transient conduction along supply lines only					
ISO 7637-3	Road vehicles – Electrical disturbance by conduction and coupling – Part 3: Vehicles with nominal 12 V or 24 V supply voltage – Electrical transient transmission by capacitive and inductive coupling via lines other than supply lines					
ISO/TR 10305-1	Road vehicles – Calibration of electromagnetic field strength measuring devices – Part 1: Devices for measurement of electromagnetic fields at frequencies > 0 Hz					
ISO/TR 10305-2	Road vehicles – Calibration of electromagnetic field strength measuring devices – Part 2: IEEE standard for calibration of electromagnetic field sensors and probes, excluding antennas, from 9 kHz to 40 GHz					
ISO 10605	Road vehicles – Test methods for electrical disturbances from electrostatic discharge					
ISO/TS 14907-1	Road transport and traffic telematics – Electronic fee collection – Test procedures for user and fixed equipment – Part 1: Description of test procedures					
ISO/TS 14907-2	Road transport and traffic telematics – Electronic fee collection – Test procedures for user and fixed equipment – Part 2: Conformance test for the onboard unit application interface					
ISO/TS 21609	Road vehicles – (EMC) guidelines for installation of aftermarket radio frequency transmitting equipment					
ISO 11451-1	Road vehicles – Vehicle test methods for electrical disturbances from narrowband radiated electromagnetic energy – Part 1: General principles and terminology					

ISO (Automotive Immunity Requirements) continued					
Document Number	Title				
ISO 11451-2	Road vehicles – Vehicle test methods for electrical disturbances from narrowband radiated electromagnetic energy – Part 2: Off-vehicle radiation sources				
ISO 11451-3	Road vehicles – Electrical disturbances by narrowband radiated electromagnetic energy – Vehicle test methods – Part 3: On-board transmitter simulation				
ISO 11451-4	Road vehicles – Vehicle test methods for electrical disturbances from narrowband radiated electromagnetic energy – Part 4: Bulk current injection (BCI)				
ISO 11452-1	Road vehicles – Component test methods for electrical disturbances from narrowband radiated electromagnetic energy – Part 1: General principles and terminology				
ISO 11452-2	Road vehicles – Component test methods for electrical disturbances from narrowband radiated electromagnetic energy – Part 2: Absorber-lined shielded enclosure				
ISO 11452-3	Road vehicles – Component test methods for electrical disturbances from narrowband radiated electromagnetic energy – Part 3: Transverse electromagnetic mode (TEM) cell				
ISO 11452-4	Road vehicles – Component test methods for electrical disturbances from narrowband radiated electromagnetic energy – Part 4: Bulk current injection (BCI)				
ISO 11452-5	Road vehicles – Component test methods for electrical disturbances from narrowband radiated electromagnetic energy – Part 5: Stripline				
ISO 11452-7	Road vehicles – Component test methods for electrical disturbances from narrowband radiated electromagnetic energy – Part 7: Direct radio frequency (RF) power injection				
ISO 11452-8	Road vehicles – Component test methods for electrical disturbances from narrowband radiated electromagnetic energy – Part 8: Immunity to magnetic fields				
ISO 11452- 10	Road vehicles – Component test methods for electrical disturbances from narrowband radiated electromagnetic energy – Part 10: Immunity to conducted disturbances in the extended audio frequency range				
ISO 11452- 11	Road vehicles – Component test methods for electrical disturbances from narrowband radiated electromagnetic energy – Part 11: Reverberation chamber				
ISO 13766	Earth-moving machinery – Electromagnetic compatibility				

2016 AUTOMOTIVE EMC GUIDE

SAE (Automo	tive Emissions and Immunity)
Document	Title
Number	•
J1113/1	Electromagnetic Compatibility Measurement Procedures and Limits for Components of Vehicles, Boats (Up to 15 M), and Machines (Except Aircraft) (50 Hz to 18 Ghz)
J1113/2	Electromagnetic Compatibility Measurement Procedures and Limits for Vehicle Components (Except Aircraft)–Conducted Immunity, 15 Hz to 250 kHz–All Leads
J1113/3	Conducted Immunity, 250 kHz to 400 MHz, Direct Injection of Radio Frequency (RF) Power (Cancelled August 2010)
J1113/4	Immunity to Radiated Electromagnetic Fields-Bulk Current Injection (BCI) Method
J1113/11	Immunity to Conducted Transients on Power Leads
J1113/12	Electrical Interference by Conduction and Coupling – Capacitive and Inductive Coupling via Lines Other than Supply Lines
J1113/13	Electromagnetic Compatibility Measurement Procedure for Vehicle Components – Part 13: Immunity to Electrostatic Discharge
J1113/21	Electromagnetic Compatibility Measurement Procedure for Vehicle Components – Part 21: Immunity to Electromagnetic Fields, 30 MHz to 18 GHz, Absorber-Lined Chamber
J1113/24	Immunity to Radiated Electromagnetic Fields; 10 kHz to 200 MHz-Crawford TEM Cell and 10 kHz to 5 GHz-Wideband TEM Cell (Cancelled August 2010)
J1113/26	Electromagnetic Compatibility Measurement Procedure for Vehicle Components – Immunity to AC Power Line Electric Fields
J1113/27	Electromagnetic Compatibility Measurements Procedure for Vehicle Components – Part 27: Immunity to Radiated Electromagnetic Fields – Mode Stir Reverberation Method
J1113/28	Electromagnetic Compatibility Measurements Procedure for Vehicle Components–Part 28–Immunity to Radiated Electromagnetic Fields–Reverberation Method (Mode Tuning)
J1113/42	Electromagnetic Compatibility–Component Test Procedure– Part 42–Conducted Transient Emissions (Cancelled Dec 2010, Superseded by ISO 7637-2)
J1752/1	Electromagnetic Compatibility Measurement Procedures for Integrated Circuits-Integrated Circuit EMC Measurement Procedures-General and Definition
J1752/2	Measurement of Radiated Emissions from Integrated Circuits – Surface Scan Method (Loop Probe Method) 10 MHz to 3 GHz
J1752/3	Measurement of Radiated Emissions from Integrated Circuits – TEM/Wideband TEM (GTEM) Cell Method; TEM Cell (150 kHz to 1 GHz), Wideband TEM Cell (150 kHz to 8 GHz)
J551/5	Performance Levels and Methods of Measurement of Magnetic and Electric Field Strength from Electric Vehicles, Broadband, 9 kHz To 30 MHz
J551/11	Vehicle Electromagnetic Immunity-Off-Vehicle Source (Cancelled March 2010)

SAE (Automotive Emissions and Immunity) continued					
Document Number	Title				
J551/12	Vehicle Electromagnetic Immunity-On-Board Transmitter Simulation (Cancelled August 2009)				
J551/13	Vehicle Electromagnetic Immunity-Bulk Current Injection (Cancelled August 2009)				
J551/15	Vehicle Electromagnetic Immunity–Electrostatic Discharge (ESD)				
J551/16	Electromagnetic Immunity – Off-Vehicle Source (Reverberation Chamber Method) – Part 16 – Immunity to Radiated Electromagnetic Fields				
J551/17	Vehicle Electromagnetic Immunity – Power Line Magnetic Fields				
J1812	Function Performance Status Classification for EMC Immunity Testing				
J2628	Characterization-Conducted Immunity				
J2556	Radiated Emissions (RE) Narrowband Data Analysis-Power Spectral Density (PSD)				
GM					
Document Number	Title				
GMW3091	General Specification for Vehicles, Electromagnetic Compatibility (EMC)-Engl; Revision H; Supersedes GMI 12559 R and GMI 12559 V				
GMW3097	General Specification for Electrical/Electronic Components and Subsystems, Electromagnetic Compatibility-Engl; Revision H; Supersedes GMW12559, GMW3100, GMW12002R AND GMW12002V				
General Specification for Electrical/Electronic Component and Subsystems, Electromagnetic Compatibility Global EMC Component/Subsystem Validation Acceptance Proce Engl; Revision F; Contains Color; Replaces GMW12003, GMW12004 and GMW3106					
Ford					
Document Number	Title				
EMC- CS-2009.1	Component EMC Specification EMC-CS-2009.1				
FORD F-2	Electrical and Electronics System Engineering				
FORD WSF- M22P5-A1	Printed Circuit Boards, PTF, Double Sided, Flexible				
DaimlerChrysler					
Document Number	Title				
DC-10614	EMC Performance Requirements – Components				
DC-10615	Electrical System Performance Requirements for Electrical and Electronic Components				
DC-11224	EMC Performance Requirements – Components				
DC-11225	EMC Supplemental Information and Alternative Component Requirements				
DC-11223	EMC Performance Requirements – Vehicle				

2016 AUTOMOTIVE EMC GUIDE

Other Automotive Manufactu	irers
Audi TL 82466	Electrostatic Discharge
BMW 600 13.0	Electric- / Electronic components in cars
	Electromagnetic Compatibility (EMC)
BMW GS 95002	Requirements and Tests
BMW GS 95003-2	Electric- / Electronic assemblies in motor
	vehicles
Chrysler PF 9326	Electrical electronic modules and motors
FIAT 9.90110	Electric and electronic devices for motor vehicles
Freightliner 49-00085	EMC Requirements
Honda 3838Z-S5AA-L000	Noise Simulation Test
Honda 3982Z-SDA-0030	Battery Simulation Test
Hyundai/Kia ES 39110-00	EMC Requirements
Hyundai/Kia ES-95400-10	Battery Simulation Tests
Hyundai/Kia ES 96100-01	EMC Requirements
IVECO 16-2103	EMC Requirements
Lotus 17.39.01	Lotus Engineering Standard: Electromagnetic Compatibility
Mack Trucks 606GS15	EMC Requirements
MAN 3285	EMC Requirements
Mazda MES PW 67600	Automobile parts standard (electronic devices)
Mercedes A 211 000 42 99	Instruction specification of test method for E/E-components
Mercedes AV EMV	Electric aggregate and electronics in cars
Mercedes MBN 10284-2	EMC requirements and tests of E/E-systems (component test procedures)
Mercedes MBN 22100-2	Electric / electronic elements, devices in trucks
Mitsubishi ES-X82010	Gen <mark>eral</mark> specification of environment tests on automotive electronic equipment
Nissan 28401 NDS02	EMC requirements (instruction concerning vehicle and electrical)
Nissan 28400 NDS03	Low frequency surge resistance of electronic parts
Nissan 28400 NDS04	Burst and Impulse Waveforms
Nissan 28400 NDS07	Immunity against low frequency surge (induction surge) of electronic parts
Peugeot B217110	Load Dump Pulses
Porsche AV EMC EN	EMC Requirements
PSA B21 7090	EMC Requirements (electric and electronics equipment)
PSA B21 7110	EMC requirements (electric and electronics equipment)
Renault 36.00.400	Physical environment of electrical and electronic equipments
Renault 36.00.808	EMC requirements (cars and electrical / electronic components)
Scania TB1400	EMC Requirements
Scania TB1700	Load Dump Test
	•

Other Automotive Manufactu	irers
Smart DE10005B	EMC requirements (electric aggregate and electronics in cars)
Toyota TSC7001G	Engineering standard (electric noise of electronic devices)
Toyota TSC7001G-5.1	Power Supply Voltage Characteristic Test
Toyota TSC7001G-5.2	Field Decay Test
Toyota TSC7001G-5.3	Floating Ground Test
Toyota TSC7001G-5.4	Induction Noise Resistance
Toyota TSC7001G-5.5.3	Load Dump Test-1
Toyota TSC7001G-5.5.4	Load Dump Test-2
Toyota TSC7001G-5.5.5	Load Dump Test-3
Toyota TSC7001G-5.6	Over Voltage Test
Toyota TSC7001G-5.7.3	Ignition Pulse (Battery Waveforms) Test-1
Toyota TSC7001G-5.7.4	Ignition Pulse (Battery Waveforms) Test-2
Toyota TSC7001G-5.8	Reverse Voltage
Toyota TSC7006G-4.4.2	Wide Band-Width Antenna Nearby Test (0.4 to 2 GHz)
Toyota TSC7006G-4.4.3	Radio Equipment Antenna nearby Test (28 MHz)
Toyota TSC7006G-4.4.4	Mobile Phone Antenna Nearby Test (835 MHz)
Toyota TSC7018G	Static Electricity Test
Toyota TSC7025G-5	TEM Cell Test (1 to 400 MHz)
Toyota TSC7025G-6	Free Field Immunity Test (20 MHz to 1 GHz AM, 0.8 to 2 GHz PM)
Toyota TSC7025G-7	Strip Line Test (20 - 400 MHz)
Toyota TSC7026G-3.4	Narrow Band Emissions
Toyota TSC7203G	Voltage Drop / Micro Drops
Toyota TSC7508G-3.3.1	Conductive Noise in FM and TV Bands
Toyota TSC7508G-3.3.2	Conductive noise in LW, AM and SW Bands
Toyota TSC7508G-3.3.3	Radiated Noise in FM and TV Bands
Toyota TSC7508G-3.3.4	Radiated Noise in AM, SW, and LW Bands
Toyota TSC7203G	Engineering standard (ABS-TRC computers)
Toyota TXC7315G	Electrostatic Discharge (Gap Method)
Visteon ES-XU3F-1316-AA	Electronic Component - Subsystem Electromagnetic Compatibility (EMC) Requirements and Test Procedures
Volvo EMC Requirements	EMC requirements for 12V and 24V systems
Volkswagen VW TL 801 01	Electric and electronic components in cars
Volkswagen VW TL 820 66	Conducted Interference
Volkswagen VW TL 821 66	EMC requirements of electronic components - bulk current injection (BCI)
Volkswagen VW TL 823 66	Coupled Interference on Sensor Cables
Volkswagen VW TL 824 66	Immunity Against Electrostatic Discharge
Volkswagen VW TL 965	Short-Distance Interference Suppression

AUTOMOTIVE GROUPS, ORGANIZATIONS, AND CONFERENCES

AUTOMOTIVE INDUSTRY GROUPS

Auto Alliance

http://www.autoalliance.org

Automotive Council UK

http://www.automotivecouncil.co.uk

Automotive Industry Action Group

http://www.aiag.org

Automotive Industries Association of Canada

https://www.aiacanada.com

Center for Automotive Research

http://www.cargroup.org

Eclipse Automotive Working group

http://www.eclipse.org/org/workinggroups/autowg.php

European Automobile Manufacturers Association

http://www.acea.be

German Association of the Automotive Industry

https://www.vda.de/en

Motor Trades Association of Australia

http://www.mtaa.com.au

National Automobile Dealers Association

https://www.nada.org

Shanghai Automotive Industry Corporation

http://www.chinacsrmap.org/index CN.asp

TEST LABS

Cetecom

http://www.cetecom.com/en/products-services/testing.html

CKC Laboratories

http://www.ckc.com/service/emc-testing/ automotive-emc-testing/

Dayton T. Brown

http://www.dtbtest.com/EMI-Testing-EMC-Testing.aspx

Elite Electronic Engineering

http://www.elitetest.com/testing-services/emc-testing/automotive-truck-emc-testing

Intertek

http://www.intertek.com/automotive/electrical/emc-testing/

MET Laboratories

http://www.metlabs.com/services/emcemi-testing/

National Technical Systems (NTS)

https://www.nts.com/services/industry_specific/automotive

Northwest EMC

http://www.nwemc.com/emc-testing-capabilities/military-aerospace-and-automotive-emc-testing

TÜV SÜD America

https://www.tuv-sud-america.com/us-en

Underwriters labs

http://services.ul.com/service/emc-automotive-testing/

Yazaki Testing laboratory

http://www.yazakiemc.com/wp/

AUTOMOTIVE DISCUSSION GROUPS ON LINKEDIN

ASQ Automotive Division

Automotive Active Safety / Passive Safety

Auto OEM Network - World's Largest Automotive Group

Automotive Careers

Automotive Cyber Security

Automotive Electrical and Electronics Manufacturing

Automotive Electronics and Embedded Software

Automotive Electronics Community

Automotive EMC Troubleshooting Experts

Automotive Engineers

Automotive Industry Innovation Group

Automotive Industry Professionals

Automotive Industry Professionals Worldwide

Automotive Infotainment, Telematics & Connectivity

Automotive Infotainment Testing

Automotive Innovation

Automotive Management Professionals

Automotive OEM Professionals

Automotive PRO Network

Automotive Quality Professionals

Automotive Sensors and Electronics

Automotive Systems Engineers

AUTOMOTIVE GROUPS, ORGANIZATIONS, AND CONFERENCES CONTINUED

Automotive Testing

Center for Automotive Research - CAR

Electromagnetic Compatibility Automotive Group

ISO 26262 in Automotive Functional Safety

Managers of Automotive

The Automotive Engineer

The Next Mobility: Automotive & Transportation Indus-

try Innovationt

EMC STANDARDS ORGANIZATIONS

ANSI

http://www.ansi.org

ANSI Accredited C63

http://c63.org/index.htm

CISPR

http://www.iec.ch/emc/iec_emc/iec_emc_players_cispr.htm

ETSI

http://www.etsi.org

IEC

http://iec.ch

IEEE Standards Association

http://standards.ieee.org

SAE

http://www.sae.org

SAE EMC Standards Committee

http://www.sae.org/standards/

AUTOMOTIVE EMC ORGANIZATIONS

Automotive EMC (www.autoemc.net)

AUTOMOTIVE ELECTRONICS CONFERENCES

The following is a partial listing of major automotive electronics conferences held in 2016 or planned for 2017. If your conference is not listed, please contact: info@interferencetechnology.com.

IEEE Vehicular Technology Conference

http://www.ieeevtc.org/

VTC will bring together individuals from academia, industry and government to discuss and exchange ideas in the fields of mobile, wireless and vehicular technology as well as the applications and services associated with such technology. Features include world-class plenary speakers, panel sessions, tutorials, and both technical and application-based sessions.

APEC

http://www.apec-conf.org/

APEC focuses on the practical and applied aspects of the power electronics business. The conference addresses issues of immediate and long term importance to the participating power electronics engineer.

The SEMA Show

https://www.semashow.com/

This event takes place November 1 - November 4, 2016 at the Las Vegas Convention Center located at 3150 Paradise Road, Las Vegas, NV 89109. The SEMA Show is the premier automotive specialty products trade event in the world. It draws the industry's brightest minds and hottest products to one place, the Las Vegas Convention Center. In addition, the SEMA Show provides attendees with educational seminars, product demonstrations, special events, networking opportunities and more.

Automotive Sensors

http://www.automotivesensors2016.com/

This event will bring together leading experts in automotive sensors and electronics who will discuss a wide range of business and technology issues, ongoing trends, and emerging applications.

The electronica Automotive Conference

http://electronica.de/conferences/automotive-conference/

This is a communication and networking event for the entire automotive sector. Experts and decision-makers from the automotive industry in Germany and abroad come here to gather information about significant technology trends and strategies in the international automotive industry.

Automobil Elektronik Kongress

https://www.automobil-elektronik-kongress.de/en/

On 27 and 28 June 2017, the 21st Congress will be held in Ludwigsburg. We are already engaged in subject research and selection of potential speakers. We continuously strive to offer the automotive electronic world the best quality and most prestigious congress in the automotive sector.

AUTOMOTIVE GROUPS, ORGANIZATIONS, AND CONFERENCES CONTINUED

3rd International Conference Automotive Cockpit HMI USA 2016

http://www.automotive-hmi-usa.com/

The way drivers interact with their cars is evolving, driven by changes in a number of related domains – personal mobile devices, car technology, consumer electronics, demography and economics.

International Conference on Automotive Electronics

https://www.sv-veranstaltungen.de/fachbereiche/international-conference-on-automotive-electronics/?lang=en

China will be the world's largest automotive market in the future. With the International Conference on Automotive Electronics, Süddeutsche Verlag Veranstaltungen is offering an ideal platform to find out about the latest top topics at first hand and to communicate directly with experts from all over the world on 23 and 24 February 2016 in Shanghai.

2017 SAE CONFERENCES

SAE 2017 Connect to Car.

January 5, 2017 Las Vegas, Nevada, USA

Symposium on International Automotive Technology 2017

January 18-21, 2017 Pune, India

SAE 2017 Hybrid and Electric Vehicle Technologies Symposium

February 7-9, 2017 San Diego, California, USA

SAE 2017 On-Board Diagnostics

Symposium - Europe

February 27-March 1, 2017 Torino, Italy

SAE 2017 North American International Powertrain Conference

September 13-15, 2017

Chicago, Illinois, USA

SAE 2017 On-Board Diagnostics Symposium

September 26-28, 2017 Garden Grove (Anaheim), California, USA

INDEX OF ADVERTISERS

ADVERTISER LOGO

phone #: email: website:

ADVERTISER LOGO

phone #: email: website:

ADVERTISER LOGO

phone #: email: website:

ADVERTISER LOGO

phone #: email: website:





2016 AUTOMOTIVE EMC

